



## SFP - Small Form-factor Pluggable V23818-M305-B57 Multimode 850 nm 2.125 and 1.0625 Gbit/s Fibre Channel 1.25 Gigabit Ethernet Transceiver with LC™ Connector

### Features

- Small Form-factor Pluggable (SFP) transceiver
- Fully SFP MSA compliant<sup>1)</sup>
- Advanced release mechanism
  - Easy access, even in belly to belly applications
  - Grip for easy access no tool is needed
  - Color coded black (multimode)
- Excellent EMI performance
- RJ-45 style LC<sup>™</sup> connector system
- Single power supply (3.3 V)
- Extremely low power consumption of 415 mW typical
- Small size for high channel density
- UL-94 V-0 certified
- ESD Class 1C per JESD22-A114-B (MIL-STD 883D Method 3015.7)
- Compliant with FCC (Class B) and EN 55022
- For distances of up to 700 m (50 µm fiber)
- Class 1 FDA and IEC laser safety compliant
- AC/AC Coupling according to SFP MSA
- Recommendation: Infineon Cage one-piece design V23838-S5-N1 for press fit and/or solderable
- Operating case temperature: -10°C to 85°C
- SFP evaluation board V23818-S5-V2 available upon request



<sup>&</sup>lt;sup>1)</sup> Current MSA documentation can be found at www.infineon.com/fiberoptics



### **Pin Configuration**

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Figure 1 SFP Transceiver Electrical Pad Layout



### **Pin Configuration**

### **Pin Description**

Pin No.	Name	Logic Level	Function
1	V <sub>EE</sub> T	N/A	Transmitter Ground <sup>1)</sup>
2	Tx Fault	LVTTL	Transmitter Fault Indication <sup>2) 8)</sup>
3	Tx Disable	LVTTL	Transmitter Disable <sup>3)</sup>
4	MOD-DEF(2)	LVTTL	Module Definition 2 <sup>4) 8)</sup>
5	MOD-DEF(1)	LVTTL	Module Definition 1 <sup>5) 8)</sup>
6	MOD-DEF(0)	N/A	Module Definition 0 <sup>6) 8)</sup>
7	Rate Select	N/A	Not connected
8	LOS	LVTTL	Loss Of Signal <sup>7) 8)</sup>
9	V <sub>EE</sub> R	N/A	Receiver Ground <sup>1)</sup>
10	V <sub>EE</sub> R	N/A	Receiver Ground <sup>1)</sup>
11	V <sub>EE</sub> R	N/A	Receiver Ground <sup>1)</sup>
12	RD-	LVPECL	Inv. Received Data Out <sup>9)</sup>
13	RD+	LVPECL	Received Data Out <sup>9)</sup>
14	V <sub>EE</sub> R	N/A	Receiver Ground <sup>1)</sup>
15	V <sub>CC</sub> R	N/A	Receiver Power
16	V <sub>CC</sub> T	N/A	Transmitter Power
17	V <sub>EE</sub> T	N/A	Transmitter Ground <sup>1)</sup>
18	TD+	LVPECL	Transmit Data In <sup>10)</sup>
19	TD-	LVPECL	Inv. Transmit Data In <sup>10)</sup>
20	V <sub>EE</sub> T	N/A	Transmitter Ground <sup>1)</sup>

<sup>1)</sup> Common transmitter and receiver ground within the module.

<sup>2)</sup> A high signal indicates a laser fault of some kind and that laser is switched off.

<sup>3</sup> A low signal switches the transmitter on. A high signal or when not connected switches the transmitter off.

<sup>4)</sup> MOD-DEF(2) is the data line of two wire serial interface for serial ID.

<sup>5)</sup> MOD-DEF(1) is the clock line of two wire serial interface for serial ID.

<sup>6)</sup> MOD-DEF(0) is grounded by the module to indicate that the module is present.

<sup>7)</sup> A low signal indicates normal operation, light is present at receiver input. A high signal indicates the received optical power is below the worst case receiver sensitivity.

<sup>8)</sup> Should be pulled up on host board to  $V_{CC}$  by 4.7 - 10 k $\Omega$ .

 $^{9}$  AC coupled inside the transceiver. Must be terminated with 100  $\Omega$  differential at the user SERDES.

 $^{\scriptscriptstyle 10)}$  AC coupled and 100  $\Omega$  differential termination inside the transceiver.



### Description

The Infineon Fibre Channel / Gigabit Ethernet multimode transceiver – part of Infineon Small Form Factor transceiver family – is based on the Physical Medium Depend (PMD) sublayer and baseband medium, type 1000 Base-SX (short wavelength) as specified in IEEE Std 802.3, Fibre Channel

FC-PI (Rev. 13) 200-M5-SN-I, 200-M6-SN-I,

FC-PI (Rev. 13) 100-M5-SN-I, 100-M6-SN-I.

The appropriate fiber optic cable is 62.5 µm or 50 µm multimode fiber with LC<sup>™</sup> connector.

### Link Length as Defined by IEEE and Fibre Channel Standards

Fiber Type	F	Reach	Unit
	min. <sup>1)</sup>	max. <sup>2)</sup>	
at 1.0625 Gbit/s			
50 μm, 2000 MHz*km	0.5	860	meters
50 μm, 500 MHz*km	0.5	500	
50 μm, 400 MHz*km	0.5	450	
62.5 μm, 200 MHz*km	0.5	300	
62.5 μm, 160 MHz*km	0.5	250	
at 1.25 Gbit/s	· ·	·	
50 μm, 500 MHz*km	2	550	meters
50 μm, 400 MHz*km	2	500	
62.5 μm, 200 MHz*km	2	275	
62.5 μm, 160 MHz*km	2	220	
at 2.125 Gbit/s			
50 μm, 2000 MHz*km	0.5	500	meters
50 μm, 500 MHz*km	0.5	300	
50 μm, 400 MHz*km	0.5	260	
62.5 μm, 200 MHz*km	0.5	150	
62.5 μm, 160 MHz*km	0.5	120	

<sup>1)</sup> Minimum reach as defined by IEEE and Fibre Channel Standards. A 0 m link length (loop-back connector) is supported.

<sup>2)</sup> Maximum reach as defined by IEEE and Fibre Channel Standards. Longer reach possible depending upon link implementation.



The Infineon SFP multimode transceiver is a single unit comprised of a transmitter, a receiver, and an LC<sup>™</sup> receptacle.

This transceiver supports the LC<sup>™</sup> connectorization concept. It is compatible with RJ-45 style backpanels for high end datacom and telecom applications while providing the advantages of fiber optic technology.

The module is designed for low cost SAN, LAN, WAN, Fibre Channel applications. It can be used as the network end device interface in mainframes, workstations, servers, and storage devices, and in a broad range of network devices such as bridges, routers, hubs, and local and wide area switches.

This transceiver operates at 1.0625/1.25/2.125 Gbit/s from a single power supply (+3.3 V). The full differential data inputs and outputs are LVPECL compatible.

### **Functional Description of SFP Transceiver**

This transceiver is designed to transmit serial data via multimode cable.



Figure 2 Functional Diagram



The receiver component converts the optical serial data into LVPECL compatible electrical data (RD+ and RD–). The Loss Of Signal (LOS) shows whether an optical signal is present.

The transmitter converts LVPECL compatible electrical serial data (TD+ and TD–) into optical serial data. Data lines are differentially 100  $\Omega$  terminated.

The transmitter contains a laser driver circuit that drives the modulation and bias current of the laser diode. The currents are controlled by a power control circuit to guarantee constant output power of the laser over temperature and aging. The power control uses the output of the monitor PIN diode (mechanically built into the laser coupling unit) as a controlling signal, to prevent the laser power from exceeding the operating limits.

Single fault condition is ensured by means of an integrated automatic shutdown circuit that disables the laser when it detects laser fault to guarantee the laser Eye Safety.

The transceiver contains a supervisory circuit to control the power supply. This circuit makes an internal reset signal whenever the supply voltage drops below the reset threshold. It keeps the reset signal active for at least 140 milliseconds after the voltage has risen above the reset threshold. During this time the laser is inactive.

A low signal on TxDis enables transmitter. If TxDis is high or not connected the transmitter is disabled.

The information which kind of SFP module has been plugged into an SFP port can be read through the MOD-DEF interface. The information is stored in an I<sup>2</sup>C-Eprom inside the SFP Transceiver.



# **Regulatory Compliance**

Feature	Standard	Comments
CE File: 1400	Compliant with 89/336/EEC	EN 55022 EN 55024
ESD: Electrostatic Discharge to the Electrical Pins	EIA/JESD22-A114-B (MIL-STD 883D method 3015.7)	Class 1C
Immunity: Against Electrostatic Discharge (ESD) to the Duplex LC Receptacle	EN 61000-4-2 IEC 61000-4-2	Discharges ranging from $\pm 2$ kV to $\pm 15$ kV on the receptacle cause no damage to transceiver (under recommended conditions).
Immunity: Against Radio Frequency Electromagnetic Field	EN 61000-4-3 IEC 61000-4-3	With a field strength of 3 V/m, noise frequency ranges from 10 MHz to 2 GHz. No effect on transceiver performance between the specification limits.
Emission: Electromagnetic Interference (EMI)	FCC 47 CFR Part 15, Class B EN 55022 Class B CISPR 22	Noise frequency range: 30 MHz to 18 GHz
SFP V23818-M305-B57 Tested To Comply With FCC Standards FOR HOME OR OFFICE USE File: 1402		<ul> <li>This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions:</li> <li>1 This device may not cause harmful interference.</li> <li>2 This device must accept any interference received, including interference that may cause undesired operation.</li> </ul>



### **Technical Data**

### **Absolute Maximum Ratings**

Parameter	Symbol	Lim	Unit	
		min.	max.	
Package Power Dissipation			0.5	W
Data Input Levels			V <sub>CC</sub> +0.5	V
Differential Data Input Voltage Swing	$V_{ID}pk-pk$		5	
Storage Ambient Temperature		-40	85	°C
V <sub>CC</sub> max			5.5	V
ECL-Output Current Data			50	mA

Exceeding any one of these values may destroy the device immediately.

### **Recommended Operating Conditions**

Parameter	Symbol		Unit		
		min.	typ.	max.	
Case Temperature	T <sub>C</sub>	-10		85	°C
Power Supply Voltage	$V_{\rm CC} - V_{\rm EE}$	3.1	3.3	3.5	V
Transmitter			<b>-</b>		•
Differential Data Input Voltage Swing	$V_{ID}pk-pk$	500		3200	mV
Receiver			·		
Input Center Wavelength	λ <sub>C</sub>	770		860	nm

The electro-optical characteristics described in the following tables are valid only for use under the recommended operating conditions.



# **Transmitter Electro-Optical Characteristics**

Transmitter	Symbol		Limit Values		
		min.	typ.	max.	
Launched Power (Average) <sup>1)</sup>	Po	-9.5	-6	-4	dBm
Optical Modulation Amplitude <sup>2)</sup> 2.125 Gbit/s 1.25/1.0625 Gbit/s	OMA	196 156	450 450		μW
Center Wavelength	λ <sub>C</sub>	830	850	860	nm
Spectral Width (RMS)	σι			0.85	
Relative Intensity Noise	RIN			-117	dB/Hz
Extinction Ratio (Dynamic)	ER	9	13		dB
Total Tx Jitter	TJ		40	80	ps
Reset Threshold <sup>3)</sup>	$V_{TH}$	2.5	2.75	2.99	V
Reset Time Out <sup>3)</sup>	t <sub>RES</sub>	140	240	560	ms
Rise Time, 20% - 80%	t <sub>R</sub>			150	ps
Supply Current			45	65	mA

 $^{\scriptscriptstyle 1)}$  Into multimode fiber, 62.5  $\mu m$  or 50  $\mu m$  diameter.

<sup>2)</sup> Fibre Channel PI Standard.

<sup>3)</sup> Laser power is shut down if power supply is below  $V_{\text{TH}}$  and switched on if power supply is above  $V_{\text{TH}}$  after  $t_{\text{RES}}$ .

### **Receiver Electro-Optical Characteristics**

Receiver	Symbol		Limit Values		
		min.	typ.	max.	
Sensitivity (Average Power) <sup>1)</sup> 2.125 Gbit/s 1.25/1.0625 Gbit/s	P <sub>IN</sub>		-18.5 -19.5	-16 -17	dBm
Saturation (Average Power)	P <sub>SAT</sub>	0			dBm
Min. Optical Modulation Amplitude <sup>2)</sup> 2.125 Gbit/s	OMA		24	49	μW
<ul> <li>1.0625 Gbit/s</li> <li>Stressed Receiver Sensitivity</li> <li>50 μm Fiber<sup>3)</sup></li> <li>2.125 Gbit/s</li> <li>1.0625 Gbit/s</li> </ul>	SPIN 50 µm		19 29 24	31 96 55	μW



### Receiver Electro-Optical Characteristics (cont'd)

Receiver	Symbol		Limit Va	lues	Unit	
		min.	typ.	max.		
Stressed Receiver Sensitivity 62.5 µm Fiber <sup>3)</sup>	SPIN 62.5 µm				μW	
2.125 Gbit/s 1.0625 Gbit/s			34 32	109 67		
Loss Of Signal (LOS) Assert Level <sup>4)</sup>	P <sub>LOSA</sub>	-30	-25		dBm	
Loss Of Signal (LOS) Deassert Level <sup>5)</sup>	P <sub>LOSD</sub>		-23	-18	dBm	
Loss Of Signal (LOS) Hysteresis	$P_{\rm LOSA}$ - $P_{\rm LOSD}$	0.5	2		dB	
Loss Of Signal (LOS) Assert Time	t <sub>ASS</sub>			100	μs	
Loss Of Signal (LOS) Deassert Time	t <sub>DAS</sub>			350	μs	
Receiver 3 dB cut off Frequency <sup>2)</sup>				2.5	GHz	
Receiver 10 dB cut off Frequency <sup>2)</sup>				6	GHz	
Differential Data Output Voltage Swing <sup>6)</sup>	V <sub>OD</sub> pk-pk	500	700	1230	mV	
Return Loss of Receiver	ORL	12			dB	
Supply Current <sup>7)</sup>			80	90	mA	

<sup>1)</sup> Average optical power at which the BER is  $1 \times 10^{-12}$ . Measured with a  $2^7 - 1$  NRZ PRBS and ER = 9 dB.

<sup>2)</sup> Fibre Channel PI Standard.

<sup>3)</sup> Measured at the given Stressed Receiver Eye Closure Penalty and DCD component given in Fibre Channel PI Standard (2.03/2.18 dB & 40/80 ps).

<sup>4)</sup> An increase in optical power above the specified level will cause the LOS output to switch from a high state to a low state.

<sup>5)</sup> A decrease in optical power below the specified level will cause the LOS to change from a low state to a high state.

<sup>6)</sup> AC/AC for data. Load 50  $\Omega$  to GND or 100  $\Omega$  differential. For dynamic measurement a tolerance of 50 mV should be added.

<sup>7)</sup> Supply current excluding Rx output load.



# Timing of Control and Status I/O

Parameter	Symbol	Limit	Values	Unit	Condition
		min.	max.		
Tx Disable Assert Time	t_off		10	μs	Time from rising edge of Tx Disable to when the optical output falls below 10% of nominal.
Tx Disable Negate Time	t_on		1	ms	Time from falling edge of Tx Disable to when the modulated optical output rises above 90% of nominal.
Time to Initialize, Including Reset of Tx Fault	t_init		300		From power on or negation of Tx Fault using Tx Disable.
Tx Fault Assert Time	t_fault		100	μs	Time from fault to Tx Fault on.
Tx Disable to Reset	t_reset	10			Time Tx Disable must be held high to reset Tx Fault.
LOS Assert Time	t_loss_on		100		Time from LOS state to Rx LOS assert.
LOS Deassert Time	t_loss_off		100		Time from non-LOS state to Rx LOS deassert.
l²C Bus Clock Rate	f_i2cbus_ clock		100	kHz	



## Eye Safety

This laser based single mode transceiver is a Class 1 product. It complies with IEC 60825-1 and FDA 21 CFR 1040.10 and 1040.11.

To meet laser safety requirements the transceiver shall be operated within the Absolute Maximum Ratings.

# Attention: All adjustments have been made at the factory prior to shipment of the devices. No maintenance or alteration to the device is required. Tampering with or modifying the performance of the device will result in voided product warranty.

Note: Failure to adhere to the above restrictions could result in a modification that is considered an act of "manufacturing", and will require, under law, recertification of the modified product with the U.S. Food and Drug Administration (ref. 21 CFR 1040.10 (i)).

### Laser Data

Wavelength	850 nm
Total Output Power (as defined by IEC: 7 mm aperture at 14 mm distance)	< 675 μW
Total Output Power (as defined by FDA: 7 mm aperture at 20 cm distance)	< 70 µW
Beam Divergence	12°



### Figure 3 Required Labels



Figure 4 Laser Emission



### **Application Notes**

### **EMI-Recommendations**

To avoid electromagnetic radiation exceeding the required limits please take note of the following recommendations.

When Gigabit switching components are found on a PCB (multiplexers, clock recoveries etc.) any opening of the chassis may produce radiation also at chassis slots other than that of the device itself. Thus every mechanical opening or aperture should be as small as possible.

On the board itself every data connection should be an impedance matched line (e.g. strip line, coplanar strip line). Data, Datanot should be routed symmetrically, vias should be avoided. A terminating resistor of 100  $\Omega$  should be placed at the end of each matched line. An alternative termination can be provided with a 50  $\Omega$  resistor at each (D, Dn). In DC coupled systems a thevenin equivalent 50  $\Omega$  resistance can be achieved as follows: for 3.3 V: 125  $\Omega$  to  $V_{\rm CC}$  and 82  $\Omega$  to  $V_{\rm EE}$ , for 5 V: 82  $\Omega$  to  $V_{\rm CC}$  and 125  $\Omega$  to  $V_{\rm EE}$  at Data and Datanot. Please consider whether there is an internal termination inside an IC or a transceiver.

In certain cases signal GND is the most harmful source of radiation. Connecting chassis GND and signal GND at the plate/bezel/chassis rear e.g. by means of a fiber optic transceiver/cage may result in a large amount of radiation. Even a capacitive coupling between signal GND and chassis may be harmful if it is too close to an opening or an aperture.

If a separation of signal GND and chassis GND is not planned, it is strongly recommended to provide a proper contact between signal GND and chassis GND at every location where possible. This concept is designed to avoid hotspots. Hotspots are places of highest radiation which could be generated if only a few connections between signal and chassis GND exist. Compensation currents would concentrate at these connections, causing radiation.

By use of Gigabit switching components in a design, the return path of the RF current must also be considered. Thus a split GND plane of Tx and Rx portion may result in severe EMI problems.

The cutout should be sized so that all contact springs of the cage make good contact with the face plate.

For the SFP transceiver a connection of the SFP cage pins to chassis GND is recommended. If no separate chassis GND is available on the users PCB the pins should be connected to signal GND. In this case take care of the notes above.

Please consider that the PCB may behave like a waveguide. With an  $\varepsilon_r$  of 4, the wavelength of the harmonics inside the PCB will be half of that in free space. In this scenario even the smallest PCBs may have unexpected resonances.



The SFP transceiver can be assembled onto the host board together with all cages and host board connectors complying with the SFP multi source agreement.

### **Infineon Proposes**

### Cage:

Infineon Technologies Part Number: V23838-S5-N1

## Host board connector:

Tyco Electronics Part Number: 1367073-1



Figure 5



### **Handling Notes**



Figure 6 Installing and Removing of SFP-Transceiver





# **EEPROM Serial ID Memory Contents**

Data Address	Hex	MSA Name/Description	Content/Value
0	03	Transceiver type	SFP
1	04	Extended identifier	Serial ID
2	07	Connector type	LC
3	00	Reserved	
4	00	SONET OC-48	
5	00	SONET OC-3/12	
6	01	Gigabit Ethernet	
7	20	FC reach/technology	
8	40	FC technology	
9	0C	FC media	
10	05	FC speed	
11	01	Encoding	
12	15	Nominal bit rate	
13	00	Reserved	
14	00	Length (9 µm) x 1 km	
15	00	Length (9 µm) x 100 m	
16	32	Length (50 µm) x 10 m	
17	0F	Length (62.5 µm) x 10 m	
18	00	Length (copper) x 1 m	
19	00	Reserved	
20 - 35		Vendor name	Infineon AG
36	00	Reserved	
37 - 39		Vendor IEEE OUI	00-03-19
40 - 55		Vendor part number	V23818-M305-B57
56		Vendor revision	Infineon production code
57 - 59		Vendor revision	1.0
60 - 61		Wavelength	850
62	00	Reserved	
63		Check code (0 to 62)	
64	00	Reserved	
65	1A	Transceiver options	Tx Disable, Tx Fault, LOS
66	69	Upper bit rate margin (%)	
67	32	Lower bit rate margin (%)	
68 - 83		Vendor serial number	
84 - 91		Vendor date code	
92 - 94		Diagnostic / SFF-8472 compliance	Not implemented
95		Check code (64-94)	
96 - 127	00	Vendor specific data	



### Multimode 850 nm Fibre Channel SFP Transceiver, AC/AC TTL



Figure 7 Recommended Host Board Supply Filtering Network



Figure 8Example SFP Host Board Schematic



## **Package Outlines**

## **Package Outlines**



## Figure 9

V23818-M3	805-B57		
Revision H	listory:	2003-04-25	DS1
Previous Ve	ersion:	2002-01-24	
Page	Page Subjects (major changes since last revision)		
	Document completely revised		

For questions on technology, delivery and prices please contact the Infineon Technologies Offices in Germany or the Infineon Technologies Companies and Representatives worldwide: see our webpage at http://www.infineon.com.

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